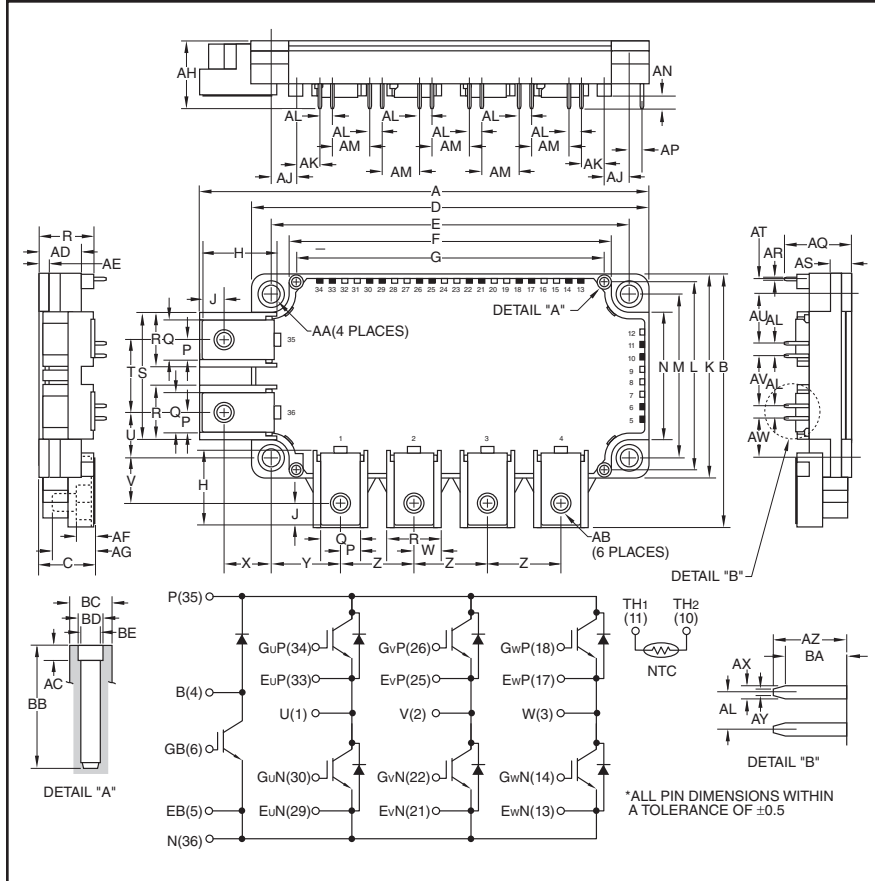


### Six IGBTMOD™ + Brake NX-Series Module 150 Amperes/600 Volts



#### Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of six IGBT Transistors in a three phase bridge configuration and a seventh IGBT with free-wheel diode for dynamic braking. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- AC Motor Control
- Motion/Servo Control
- Photovoltaic/Fuel Cell

#### Ordering Information:

Example: Select the complete module number you desire from the table below -i.e. CM150RX-12A is a 600V ( $V_{CES}$ ), 150 Ampere Six-IGBTMOD™ + Brake Power Module.

Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	5.39	136.9
B	3.03	77.1
C	0.67+0.04/-0.02	17.0+1.0/-0.5
D	4.79	121.7
E	4.33±0.02	110.0±0.5
F	3.89	99.0
G	3.72	94.5
H	0.83	21.14
J	0.37	6.5
K	2.44	62.0
L	2.26	57.5
M	1.97±0.02	50.0±0.5
N	1.53	39.0
P	0.24	6.0
Q	0.48	12.0
R	0.67	17.0
S	1.53	39.0
T	0.87	22.0
U	0.55	14.0
V	0.54	13.64
W	0.33	8.5
X	0.53	13.5
Y	0.81	20.71
Z	0.9	22.86
AA	0.22 Dia.	5.5 Dia.
AB	M5	M5
AC	0.06	1.5

Dimensions	Inches	Millimeters
AD	0.51	13.0
AE	0.12	3.0
AF	0.21	5.4
AG	0.49	12.5
AH	0.81	20.5
AJ	0.30	7.75
AK	0.28	7.25
AL	0.15	3.81
AM	0.45	11.44
AN	0.14	3.5
AP	0.16	4.06
AQ	0.78	20.05
AR	0.03	0.8
AS	0.27	7.0
AT	0.16	4.2
AU	0.61	15.48
AV	0.60	15.24
AW	0.46	11.66
AX	0.04	1.15
AY	0.02	0.65
AZ	0.29	7.4
BA	0.05	6.2
BB	0.49	12.5
BC	0.17 Dia.	4.3 Dia.
BD	0.10 Dia.	2.5 Dia.
BE	0.08 Dia.	2.1 Dia.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	150	12



Powerex, Inc., 173 Pavilion Lane, Youngwood, Pennsylvania 15697 (724) 925-7272

**CM150RX-12A**

Six IGBTMOD™ + Brake NX-Series Module

150 Amperes/600 Volts

**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	CM150RX-12A	Units
Power Device Junction Temperature	$T_j$	-40 to 150	$^\circ\text{C}$
Storage Temperature	$T_{\text{stg}}$	-40 to 125	$^\circ\text{C}$
Mounting Torque, M5 Mounting Screws	—	31	in-lb
Mounting Torque, M5 Main Terminal Screws	—	31	in-lb
Module Weight (Typical)	—	330	Grams
Isolation Voltage, AC 1 minute, 60Hz Sinusoidal	$V_{\text{ISO}}$	2500	Volts

**Inverter Sector**

Collector-Emitter Voltage (G-E Short)	$V_{\text{CES}}$	600	Volts
Gate-Emitter Voltage (C-E Short)	$V_{\text{GES}}$	$\pm 20$	Volts
Collector Current ( $T_C = 63^\circ\text{C}$ )*	$I_C$	150	Amperes
Peak Collector Current**	$I_{\text{CM}}$	300	Amperes
Emitter Current ( $T_C = 25^\circ\text{C}$ , $T_j < 150^\circ\text{C}$ )*	$I_E^{***}$	150	Amperes
Peak Emitter Current ( $T_j < 150^\circ\text{C}$ **)	$I_{\text{EM}}^{***}$	300	Amperes
Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ , $T_j < 150^\circ\text{C}$ )*	$P_C$	520	Watts

**Brake Sector**

Collector-Emitter Voltage (G-E Short)	$V_{\text{CES}}$	600	Volts
Gate-Emitter Voltage (C-E Short)	$V_{\text{GES}}$	$\pm 20$	Volts
Collector Current ( $T_C = 70^\circ\text{C}$ )*	$I_C$	75	Amperes
Peak Collector Current**	$I_{\text{CM}}$	150	Amperes
Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ , $T_j < 150^\circ\text{C}$ )*	$P_C$	280	Watts
Repetitive Peak Reverse Voltage (Clamp Diode Part)	$V_{\text{RRM}}^{***}$	600	Volts
Forward Current ( $T_C = 25^\circ\text{C}$ )*	$I_F^{***}$	75	Amperes
Forward Current (Clamp Diode Part)**	$I_{\text{FM}}^{***}$	150	Amperes

\* $T_C$ ,  $T_f$  measured point is just under the chips.

\*\*Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(\text{max})}$  rating.

\*\*\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).

**CM150RX-12A**  
**Six IGBTMOD™ + Brake NX-Series Module**  
 150 Amperes/600 Volts

**Electrical and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

**Inverter Sector**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 15mA, V_{CE} = 10V$	5	6	7	Volts
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	$\mu A$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 150A, V_{GE} = 15V, T_j = 25^\circ\text{C}$	—	1.7	2.1	Volts
		$I_C = 150A, V_{GE} = 15V, T_j = 125^\circ\text{C}$	—	1.9	—	Volts
		$I_C = 150A, V_{GE} = 15V, \text{Chip}$	—	1.6	—	Volts
Input Capacitance	$C_{ies}$		—	—	18.0	nF
Output Capacitance	$C_{oes}$	$V_{CE} = 10V, V_{GE} = 0V$	—	—	2.0	nF
Reverse Transfer Capacitance	$C_{res}$		—	—	0.6	nF
Total Gate Charge	$Q_G$	$V_{CC} = 300V, I_C = 150A, V_{GE} = 15V$	—	400	—	nC
Inductive Load	Turn-on Delay Time	$V_{CC} = 300V, I_C = 150A,$ $V_{GE} = \pm 15V,$ $R_G = 6.2\Omega, I_E = 150A,$	—	—	120	ns
	Turn-on Rise Time					
Switching Time	Turn-off Delay Time	Inductive Load Switching Operation	—	—	350	ns
	Turn-off Fall Time					
Reverse Recovery Time*	$t_{rr}$		—	—	200	ns
Reverse Recovery Charge*	$Q_{rr}$		—	5.0	—	$\mu C$
Emitter-Collector Voltage*	$V_{EC}$	$I_E = 150A, V_{GE} = 0V, T_j = 25^\circ\text{C}$	—	2.0	2.8	Volts
		$I_E = 150A, V_{GE} = 0V, T_j = 125^\circ\text{C}$	—	1.95	—	Volts
		$I_E = 150A, V_{GE} = 0V, \text{Chip}$	—	1.9	—	Volts

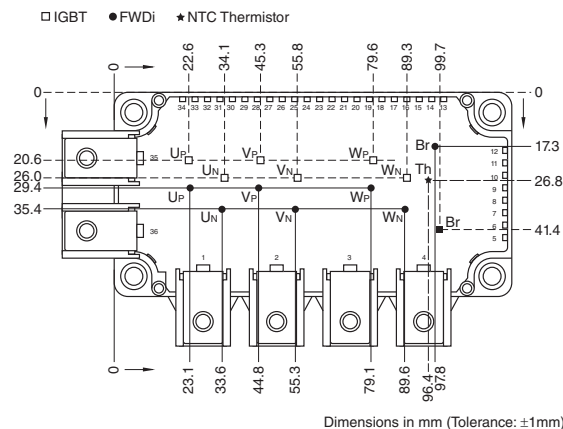
**Thermal and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case**	$R_{th(j-c)Q}$	Per IGBT	—	—	0.24	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case**	$R_{th(j-c)D}$	Per FWDi	—	—	0.46	$^\circ\text{C/W}$
Contact Thermal Resistance**	$R_{th(c-f)}$	Thermal Grease Applied	—	0.015	—	$^\circ\text{C/W}$
Internal Gate Resistance	$R_{Gint}$	$T_C = 25^\circ\text{C}$	—	0	—	$\Omega$
External Gate Resistance	$R_G$		4.1	—	41	$\Omega$

\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

\*\* $T_C, T_f$  measured point is just under the chips.

**CHIP LOCATION (TOP VIEW)**



**CM150RX-12A**

**Six IGBTMOD™ + Brake NX-Series Module**

150 Amperes/600 Volts

**Electrical and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

**Brake Sector**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 75mA$	5	6	7	Volts
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	$\mu A$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 75A, V_{GE} = 15V, T_j = 25^\circ\text{C}$	—	1.7	2.1	Volts
		$I_C = 75A, V_{GE} = 15V, T_j = 125^\circ\text{C}$	—	1.9	—	Volts
		$I_C = 75A, V_{GE} = 15V, \text{Chip}$	—	1.6	—	Volts
Input Capacitance	$C_{ies}$		—	—	9.3	nF
Output Capacitance	$C_{oes}$	$V_{CE} = 10V, V_{GE} = 0V$	—	—	1.0	nF
Reverse Transfer Capacitance	$C_{res}$		—	—	0.3	nF
Total Gate Charge	$Q_G$	$V_{CC} = 300V, I_C = 75A, V_{GE} = 15V$	—	200	—	nC
Repetitive Reverse Current*	$I_{RRM}$	$V_R = V_{RRM}$	—	—	1.0	mA
Forward Voltage Drop *	$V_F$	$I_F = 75A, T_j = 25^\circ\text{C}$	—	2.0	2.8	Volts
		$I_F = 75A, T_j = 125^\circ\text{C}$	—	1.95	—	Volts
		$I_F = 75A, \text{Chip}$	—	1.9	—	Volts

**Thermal and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case**	$R_{th(j-c)Q}$	Per IGBT	—	—	0.44	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case**	$R_{th(j-c)D}$	Per FWDi	—	—	0.85	$^\circ\text{C/W}$
Contact Thermal Resistance**	$R_{th(j-f)}$	Thermal Grease Applied	—	0.015	—	$^\circ\text{C/W}$
Internal Gate Resistance	$R_{Gint}$	$T_C = 25^\circ\text{C}$	—	0	—	$\Omega$
External Gate Resistance	$R_G$		8	—	83	$\Omega$

**NTC Thermistor Sector,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Zero Power Resistance	R	$T_C = 25^\circ\text{C}$	4.85	5.00	5.15	k $\Omega$
Deviation of Resistance	$\Delta R/R$	$T_C = 100^\circ\text{C}, R_{100} = 493\Omega$	-7.3	—	+7.8	%
B Constant	$B_{(25/50)}$	$B = (\ln R_1 - \ln R_2) / (1/T_1 - 1/T_2)^{***}$	—	3375	—	K
Power Dissipation	$P_{25}$	$T_C = 25^\circ\text{C}$	—	—	10	mW

\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

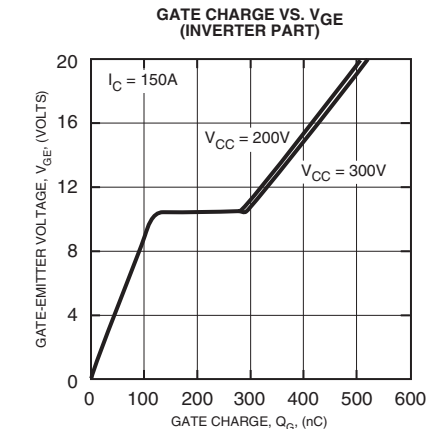
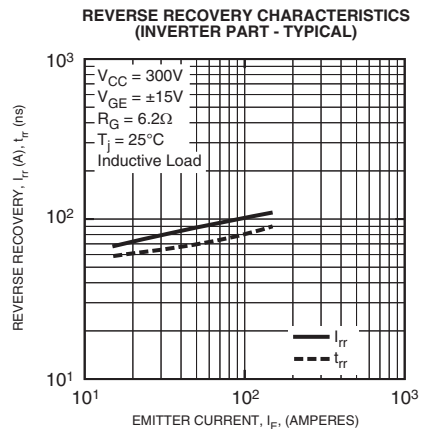
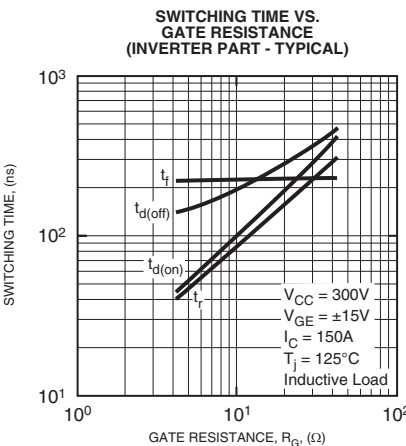
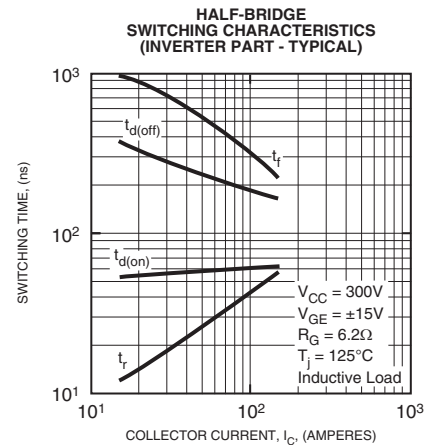
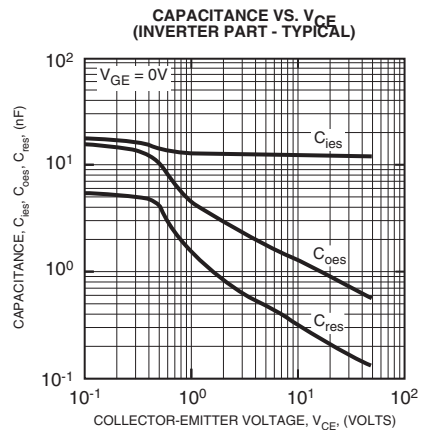
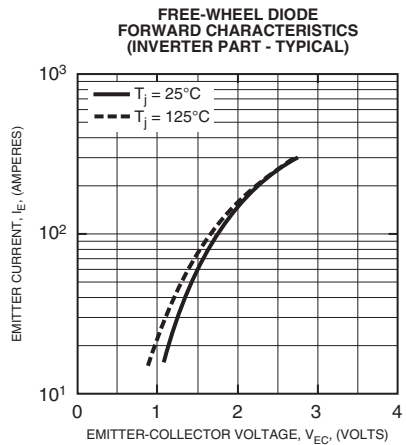
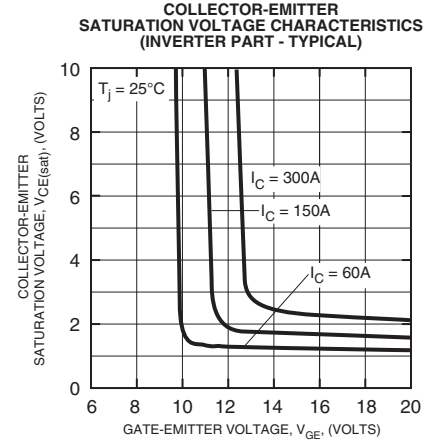
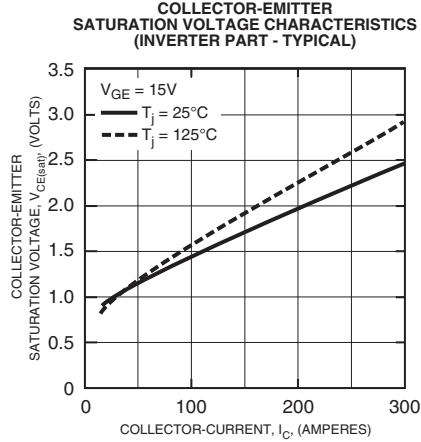
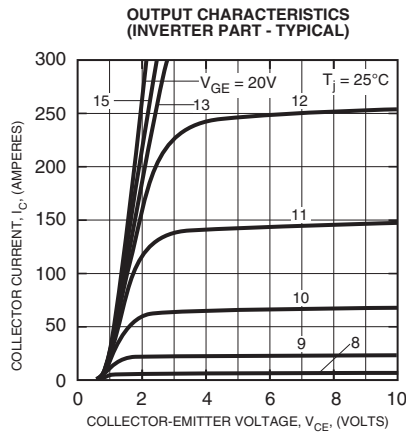
\*\* $T_C, T_f$  measured point is just under the chips.

\*\*\* $R_1$ : Resistance at Absolute Temperature  $T_1(K)$ ,  $R_2$ : Resistance at Absolute Temperature  $T_2(K)$ ,  $T(K) = t(^{\circ}\text{C}) + 273.15$



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